ABSTRACT OF THE DISCLOSURE

In a COF manufactured by bonding and mounting a semiconductor element onto a wiring pattern on a lengthy tape carrier, the wiring patterns are aligned in more than one direction with respect to a direction in which the tape carrier is fed in a layout such that increases a utilized area of the tape carrier (in other words, such that reduces useless areas). Consequently, the number of the tape carrier type semiconductor devices manufactured out of a tape carrier of a certain length can be increased without losing benefits that they can be designed in an arbitrary shape, thereby saving the manufacturing cost.

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